samtec

MECT–110–01–M–D–RA1

MECT–115–01–M–D–RA1

MECT–135–01–M–D–RA1
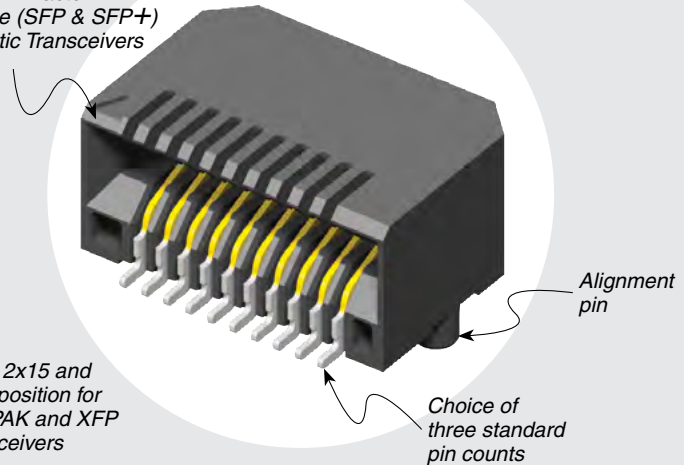
(0.80 mm) .0315"

MECT SERIES

SFP & SFP+ TRANSCEIVER INTERFACES

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MECT

Insulator Material:
Black LCP
Contact Material:
Phosphor Bronze
Plating:
Sn or Au over
100 µ" (2.54 µm) Ni
Operating Temp Range:
-55 °C to +125 °C
Current Rating:
2 A per pin
(6 pins powered)
Voltage Rating:
265 VAC
RoHS Compliant:
Yes

PROCESSING

Lead–Free Solderable:
Yes
SMT Lead Coplanarity:
(0.10 mm) .004" max (10-35)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

UL
FILE NO. E111594

Mates with:
SFP, SFP+, XFP or XENPAK transceivers

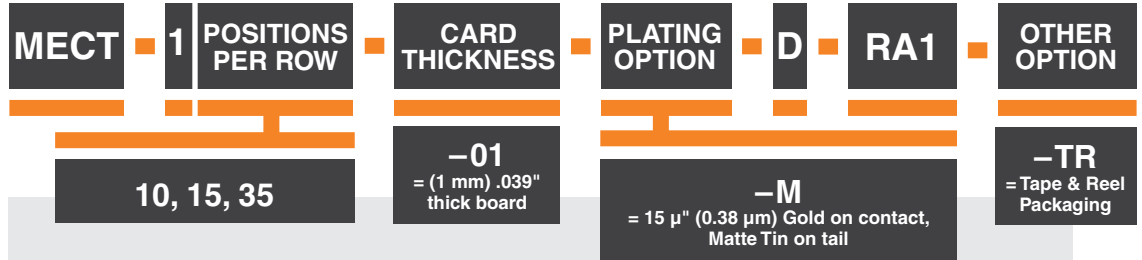*2x10 position for Small Form Factor Pluggable (SFP & SFP+) Fiber Optic Transceivers*

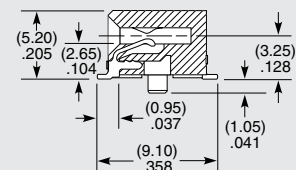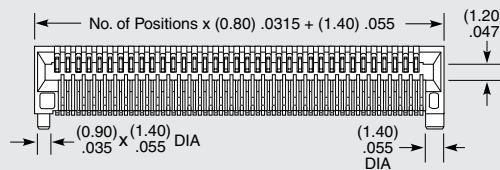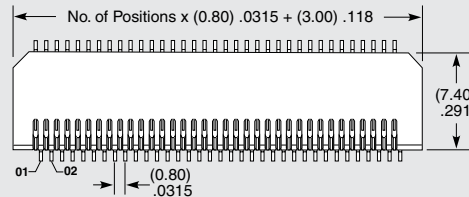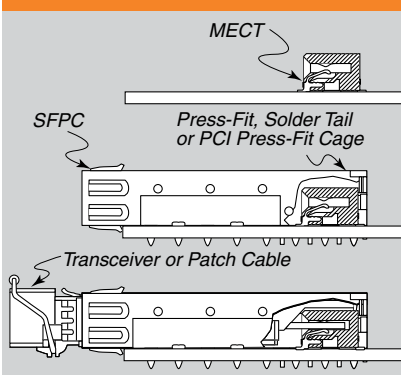*2x10, 2x15 and 2x35 position for XENPAK and XFP Transceivers*

Alignment pin

Choice of three standard pin counts

MECT	1	POSITIONS PER ROW	—	CARD THICKNESS	—	PLATING OPTION	—	D	—	RA1	—	OTHER OPTION

| | | **10, 15, 35** | | **−01**
= (1 mm) .039" thick board | | **−M**
= 15 µ" (0.38 µm) Gold on contact, Matte Tin on tail | | | | | | **−TR**
= Tape & Reel Packaging |

APPLICATION

MECT

SFPC

Press-Fit, Solder Tail or PCI Press-Fit Cage

Transceiver or Patch Cable

No. of Positions x (0.80) .0315 + (3.00) .118

(7.40) .291

01 — 02

(0.80) .0315

No. of Positions x (0.80) .0315 + (1.40) .055

(1.20) .047

(0.90) .035 x (1.40) .055 DIA

(1.40) .055 DIA

(5.20) .205

(2.65) .104

(3.25) .128

(0.95) .037

(1.05) .041

(9.10) .358

Note: Some sizes, styles and options are non-standard, non-returnable.